

	(℃)		
	(℃)		
		~	
	θ		℃
	θ ≤		

		μ				
						μ
						μ
						Ω
						Ω
- -						
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-		Ω				
-						

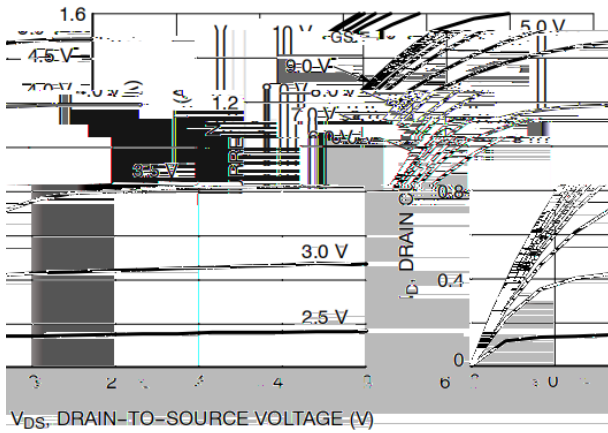


Figure 1. On-Region Characteristics

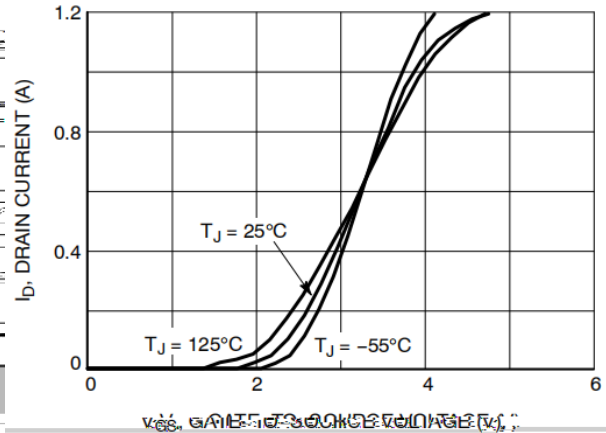


Figure 2. Transfer Characteristics

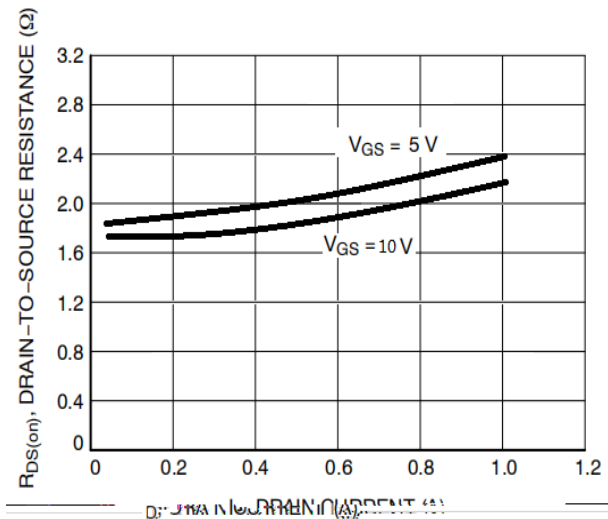


Figure 3. On-Resistance vs. Drain Current and Temperature

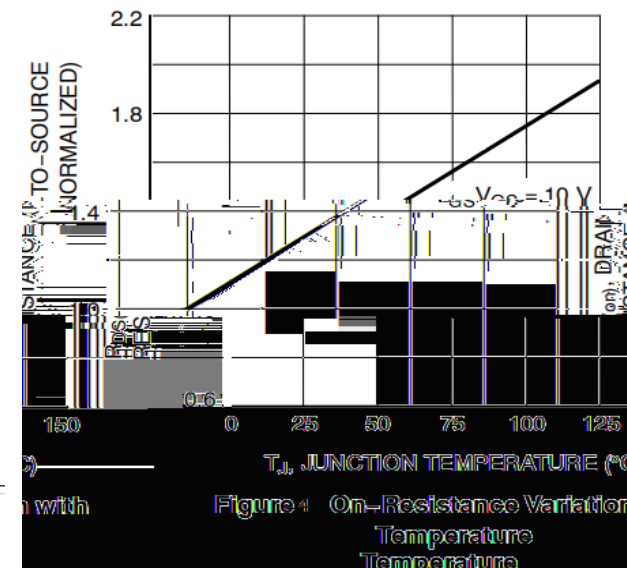


Figure 4. On-Resistance Variation with Temperature

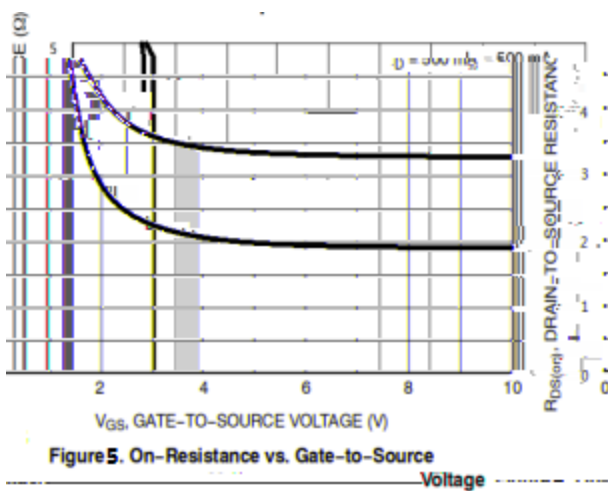


Figure 5. On-Resistance vs. Gate-to-Source Voltage

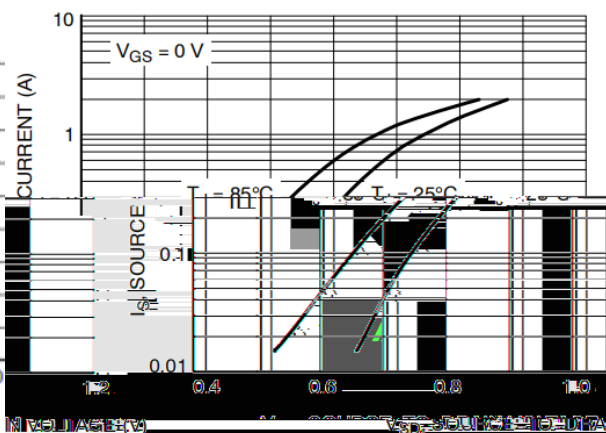


Figure 6. Diode Forward Voltage vs. Current

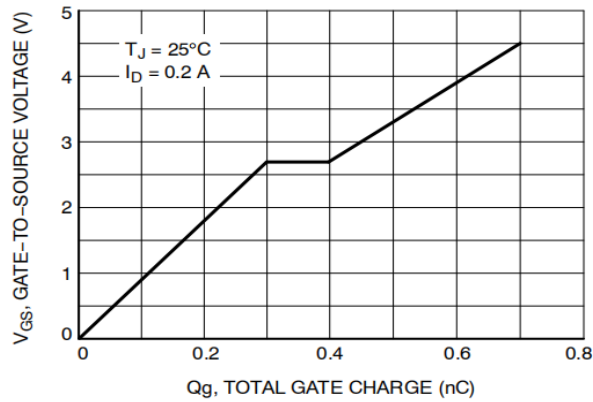


Figure 7 . Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

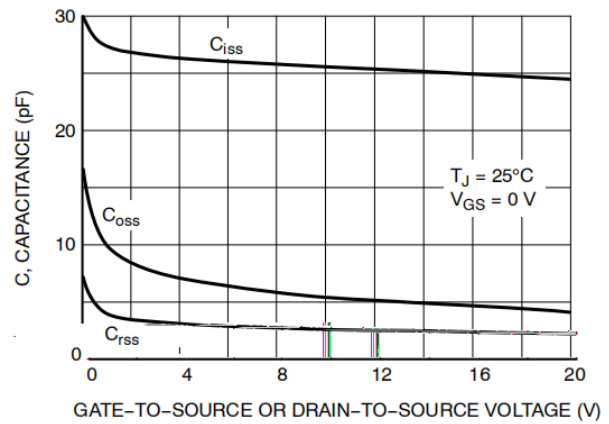


Figure 8. Capacitance Variation

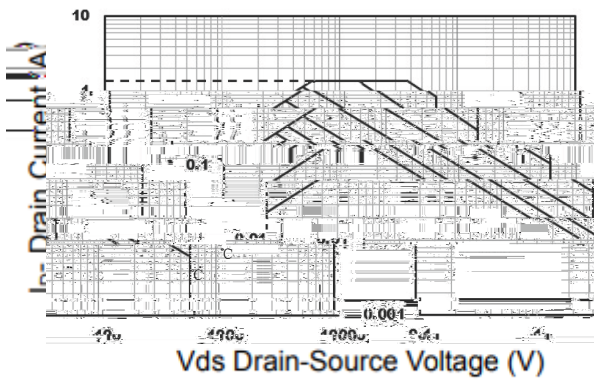


Figure 9 : Safe Operation Area

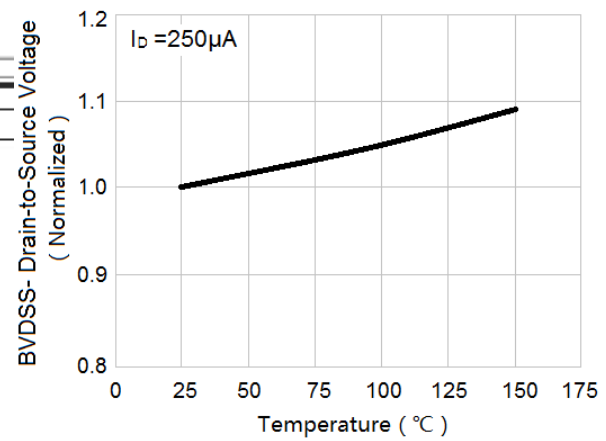
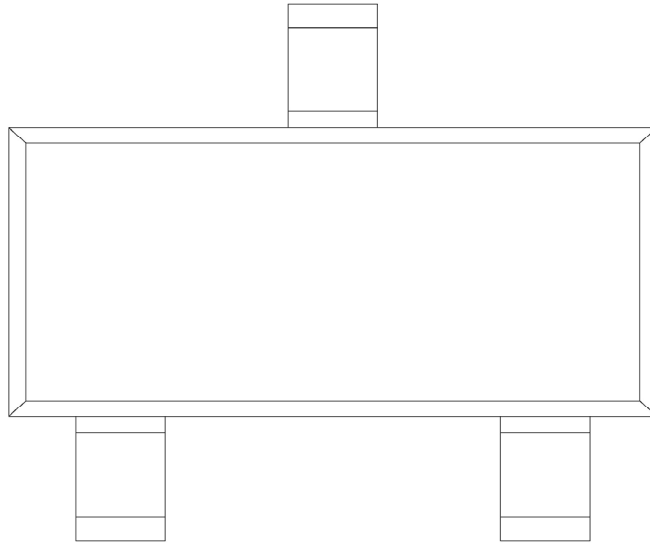


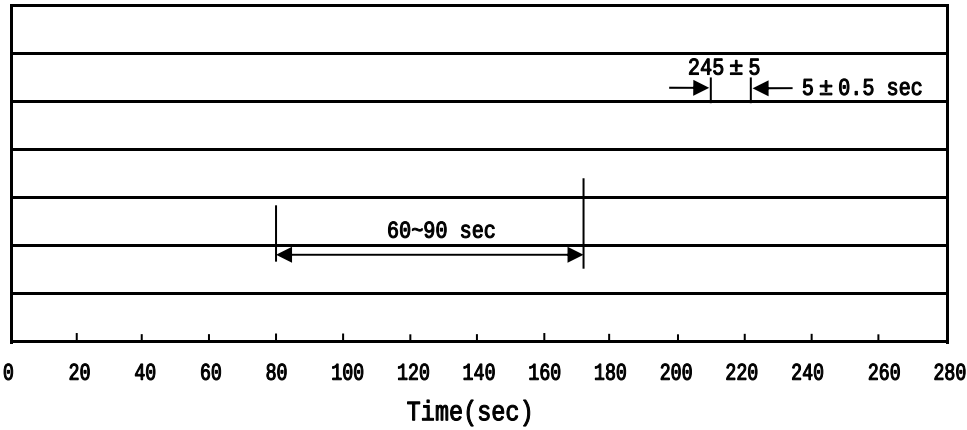
Figure 10 : Breakdown Voltage vs. Temperature



Figure 11 : Normalized Thermal Transient Impedance, Junction-to-Ambient



Temperature Profile for IR Reflow Soldering(Pb-Free)



封装形式	包装数量					包装尺寸		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱